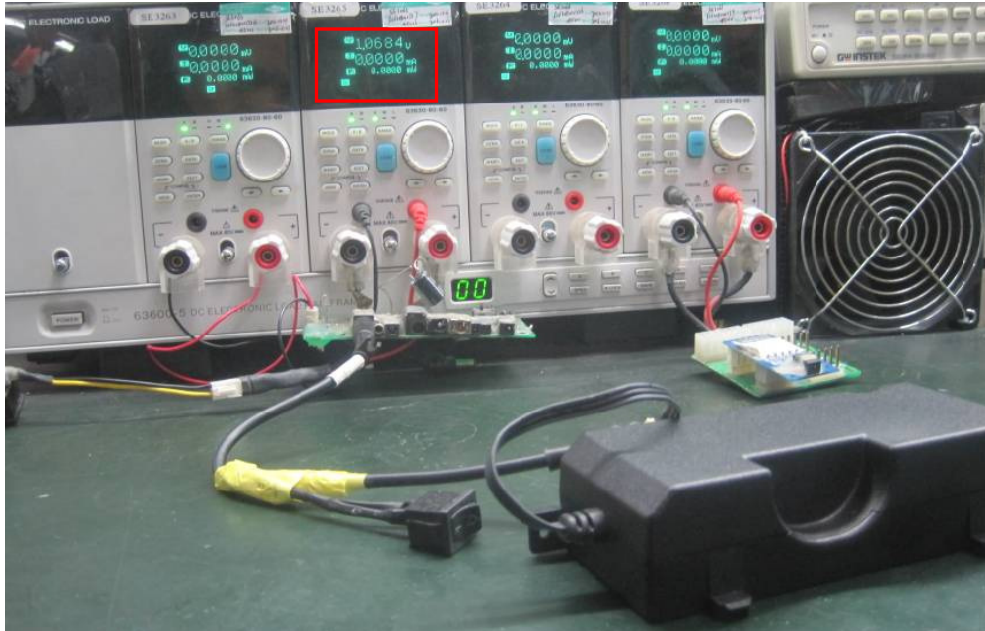


## Eight Discipline Report (8D Report)

To: <b>Customer</b>	8D report No.: <b>CPG0105</b>
From: : <b>Chicony Power Technology</b>	RMA claim No.: <b>NA</b>
CC :	Chicony Power P/N: <b>A035R004L</b>
	Customer P/N:
Submit date: <b>2016/01/21</b>	Product description: <b>35W</b>
Receive date: <b>2016/01/20</b>	Defect D/C or Lot No.: <b>151026</b>
<b>Subject : No output , (生產 / 焊錫不良/soldering issue, BD1 空焊 )</b>	
<b>D1.) 問題解決成員:Use Team Approach</b>	
主持者 (Team Leader) : <b>Cf Liu</b> 內部成員 (Internal Team Members): <div style="text-align: center; margin-top: 20px;"> <b>RD: Walt Ni / Mark Meng / Jay Huang</b>   <b>PE: Hongwu Zhang</b>   <b>IE: Yansong Tong</b>   <b>QE: Nono Chen</b>   <b>Sales: Leo Lo / Robert Cheng</b>   <b>CQS: Cecilia Sun</b>   <b>MFG: Alan Zhu</b>   <b>ME: Hai He</b>   <b>Ooba: Mary He</b> </div> 外部成員 (External Team Member):	
<b>D2.)問題說明:Problem Description:</b>	
(Note: Use <b>who, what, when, where, why, how, how many</b> to specify the Customer's problem.)	
<b>2016/01/12 Customer feedback as below:</b> <b>One of the PSU failed our printer PP run. Output is only 1V.</b>	
<b>D3.)內部或客戶的暫時解決辦法及實施日期:Implement and Verify Containment Action:</b>	
(Note: Internal / external containment action effectiveness and date.)	
<b>1. Check and do analysis for the return unit.</b> <div style="text-align: right;"><b>Owner: Hongwu Zhang    Date:2016/01/20</b></div>	
<b>D4.)不良原因確認: Define and Verify Root Causes:</b>	
(Note: Identify and verify all suspect causes, which needs explain why the problem occurred.)	

## 1. Check the fail unit

The fail unit doesn't show any case damage. We test this unit and it can not power on. The defect is the same with customer's feedback.

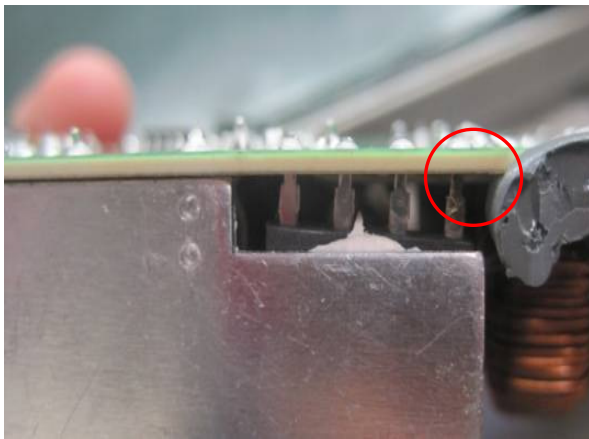
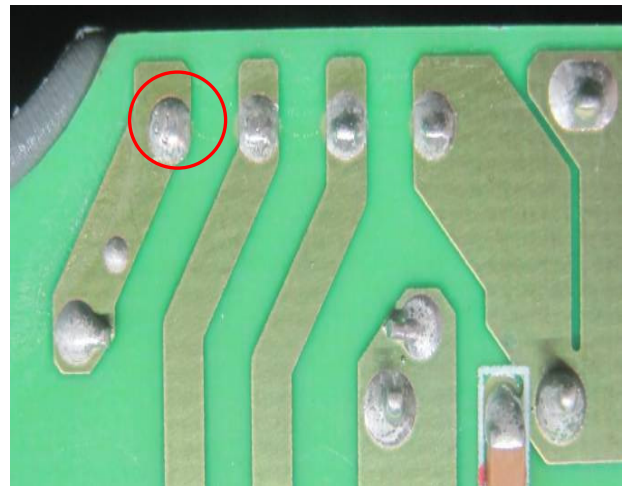
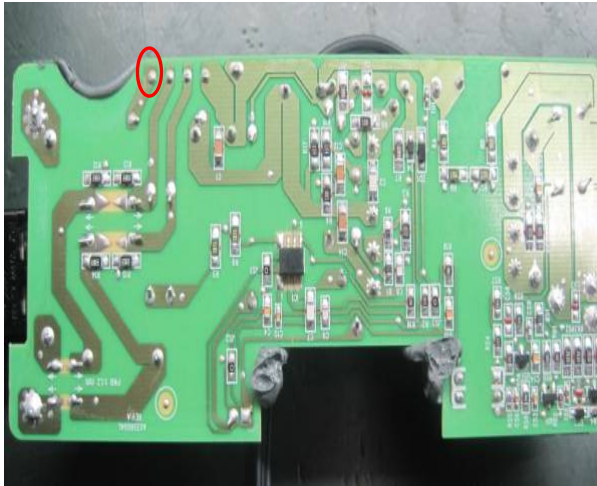


## 2. Open case & Visual inspection

(1) The top side of sample is normal.



(2) On the bottom of this sample, the pin of BD1 is excess soldering due to the pin not full out of PCBA.



**3. And we measured the pin of BD1, this pin of BD1 is open in the circuit.**

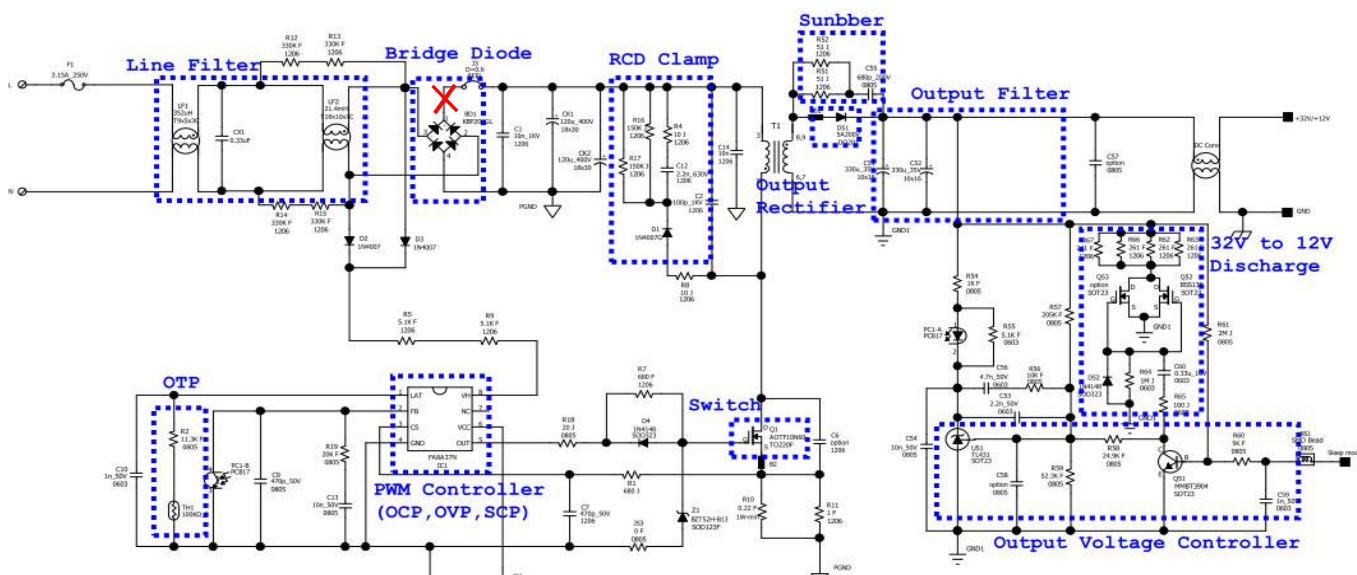


**4. When the operator inserts Heat Sink not in place for the first time, he may insert Heat Sink again. Since the BD1 is attached the glue on the Heat Sink, BD1 may be pulled out then lead not full out of PCBA.**

**5. Re-solder BD1 and then test it gain, it can power on normally.**

**6. Analysis the function of BD1 in the circuit:**

Since BD1 is open (as below red mark) in the circuit, then the main circuit is open. So this adapter can not power on.



### Conclusion:

The lead of BD1 is not full out of PCBA, caused BD1 open in the circuit. Then this adapter can not power on.

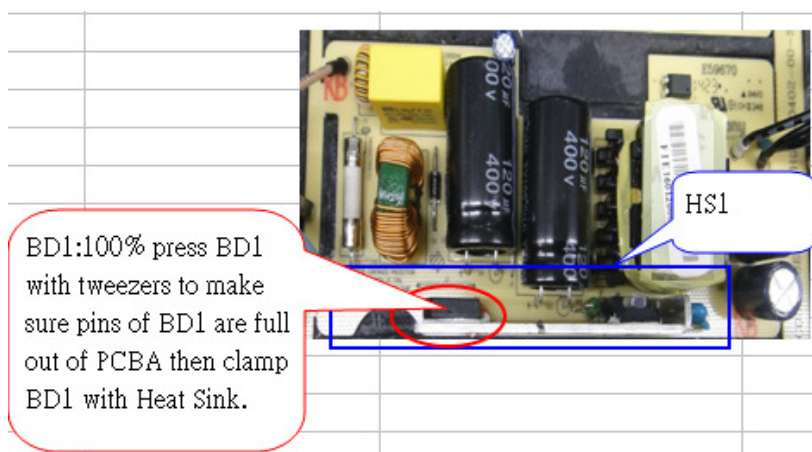
This pin touched soldering during our process, so this sample can pass all test stations then flow out to customer side.

### D5.)改善措施:Corrective Action Verification:

(Note: Be make sure the corrective actions is effective in process as well as able to fix the customer complaint problem)

#### Short-term Actions:

1. At the Heat Sink insertion station, after inserting Heat Sink, the operator should 100% press BD1 to make sure pins of BD1 are full out of PCBA. And IE modify WI for operators to follow.



Owner: Yansong Tong

2. The operator at the insertion final inspection station should 100% press the BD1 to make sure pins of BD1 are full out of PCBA. And IE modify WI for operators to follow.





**D8.)**確認並感謝問題解決成員:Check and Congratulate the Team:

**(Note:** Recognize the collective efforts of the team.)

**RD: Mark Meng / Jay Huang      PE: Hongwu Zhang      IE: Yansong Tong**

**Sales: Leo Lo / Robert Cheng      QE: Nono Chen      CQS: Cf Liu / Cecilia Sun**

**MFG: Alan Zhu      ME: Hai He      OOBA: Mary He**

<b>Signature</b>	<b>Cf Liu</b>
<b>Team Leader:</b>	
	Name – Title
<b>Signature by Approver:</b>	<b>Roy Tsai</b>
	Name-Title